

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Brian G. Lewis, et al.

Art Unit 2815

Serial No. 10/722,288

Filed: November 25, 2003

Confirmation No. 9116

For: THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS

Examiner: Clark, Jasmine Jhian B.

Allowed: December 14, 2006

REQUEST TO APPLY PREVIOUSLY PAID FEES

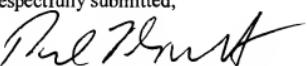
TO THE COMMISSIONER OF PATENTS AND TRADEMARKS,
SIR:

Applicant previously paid the issue fee (\$1,400.00) for the above-noted application on June 16, 2006. At that time, Applicant also paid the publication fee (\$300.00). On June 12, 2006, the Patent Office issued a notice of Withdrawal From Issue to permit reopening of the prosecution. The Withdrawal From Issue was received by this office after the payment of the issue and publications fees. A Non-Final Office Action was issued by the Patent Office on August 25, 2006. In response thereto, Applicant filed Amendment C, on November 20, 2006.

On December 19, 2006, Applicant received a new Notice of Allowance (dated December 14, 2006). **Applicant respectfully requests that the previously paid issue fee (\$1,700.00) be now applied to the payment of this issue fee.**

The Commissioner is authorized to charge any underpayment or credit any overpayment of government fees to Deposit Account No. 19-1345.

Respectfully submitted,


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